Salesforce Incentives Applicant Portal, UAT

Concept Plan Screenshots 10-08-2026





Application Pipeline Selection

*Application Pipeline Selection

NOFO 2: Facilities for Semiconductor Materials and Manufacturing Equipment

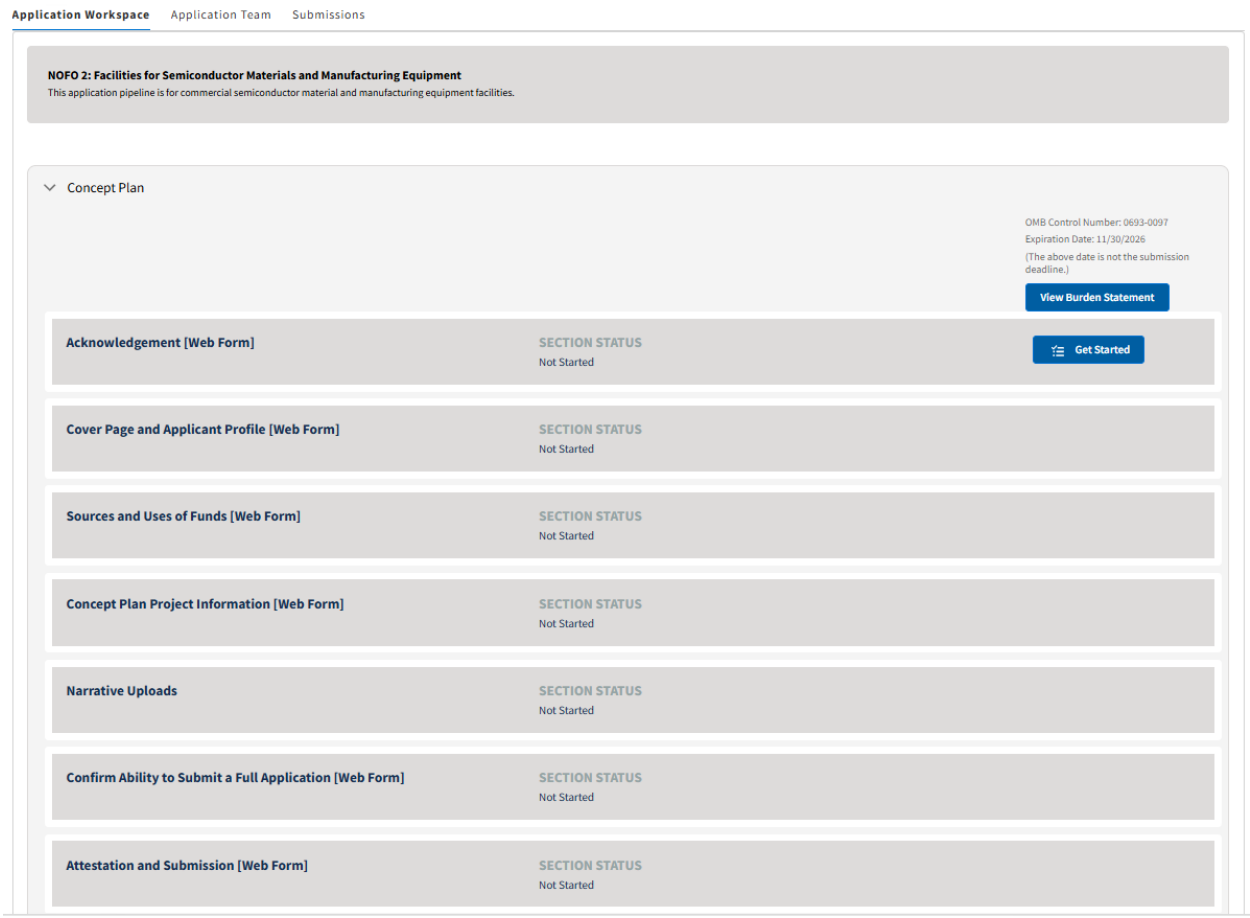
Organizations proposing multiple projects or facilities that are not co-located with one another should submit separate concept plans and applications per project location for consideration.

NOFO 2: Facilities for Semiconductor Materials and Manufacturing Equipment: This application pipeline is for commercial semiconductor material and manufacturing equipment facilities.

Next

Steps

- **Application Pipeline Selection**

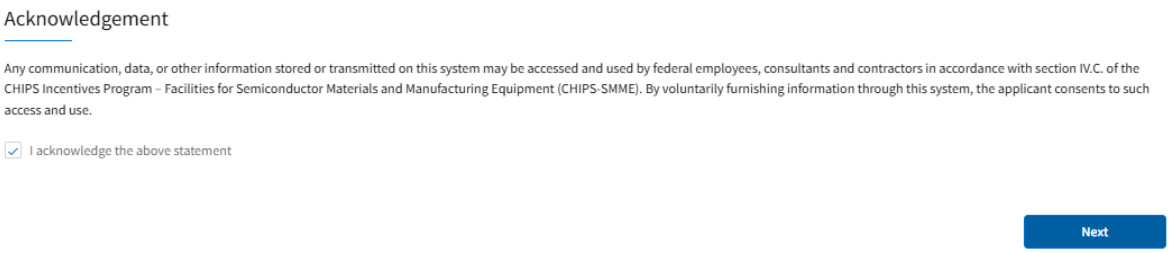

Application Workspace
Application Team
Submissions
NOFO 2: Facilities for Semiconductor Materials and Manufacturing Equipment
This application pipeline is for commercial semiconductor material and manufacturing equipment facilities.
Concept Plan
OMB Control Number: 0693-0097
Expiration Date: 11/30/2026
(The above date is not the submission deadline.)
View Burden Statement
Acknowledgement [Web Form]
SECTION STATUS
Not Started
Get Started
Cover Page and Applicant Profile [Web Form]
SECTION STATUS
Not Started
Sources and Uses of Funds [Web Form]
SECTION STATUS
Not Started
Concept Plan Project Information [Web Form]
SECTION STATUS
Not Started
Narrative Uploads
SECTION STATUS
Not Started
Confirm Ability to Submit a Full Application [Web Form]
SECTION STATUS
Not Started
Attestation and Submission [Web Form]
SECTION STATUS
Not Started

BURDEN STATEMENT

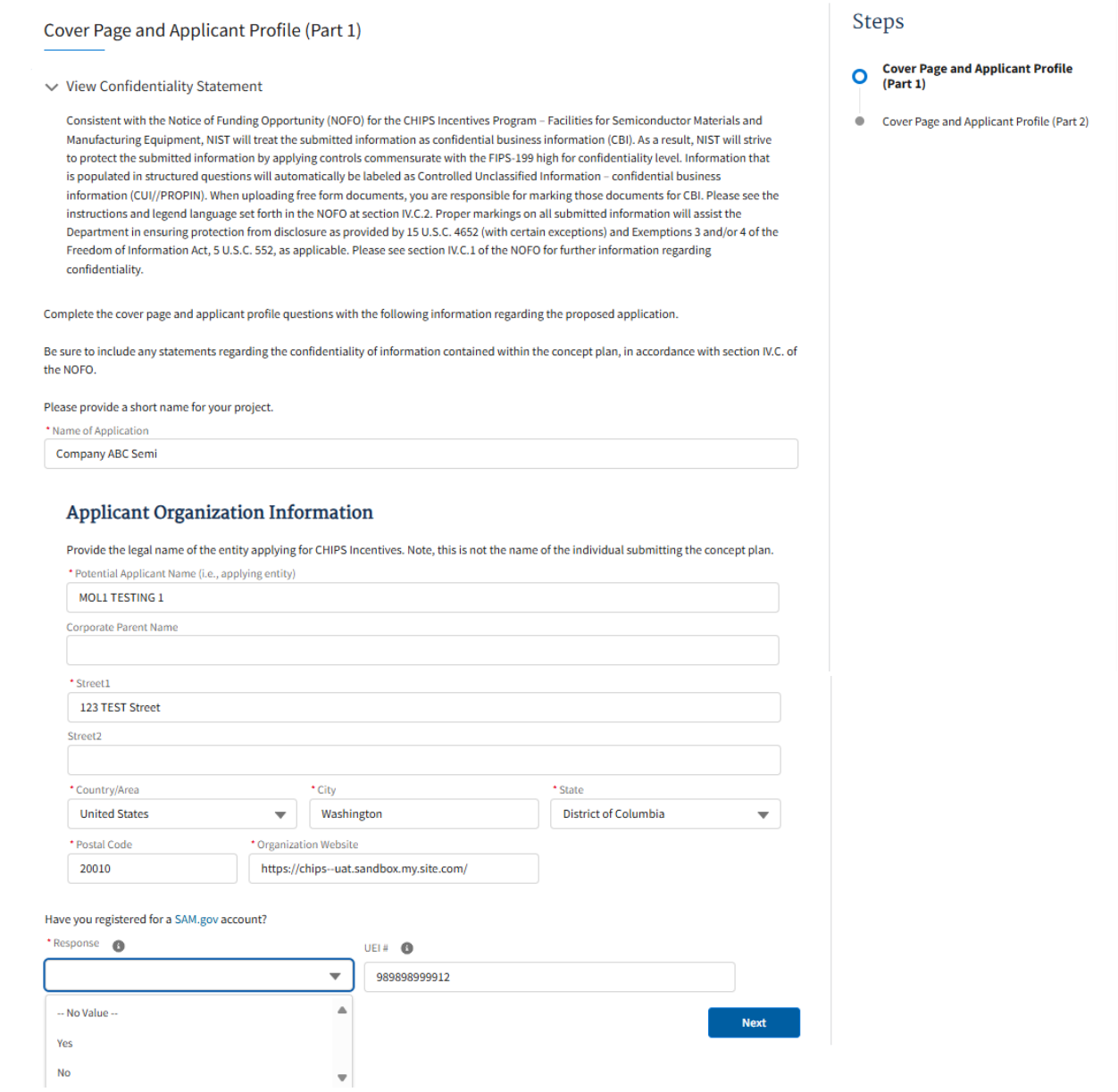
Burden Statement

A Federal agency may not conduct or sponsor, and a person is not required to respond to, nor shall a person be subject to a penalty for failure to comply with an information collection subject to the requirements of the Paperwork Reduction Act of 1995 unless the information collection has a currently valid OMB Control Number. The approved OMB Control Number for this information collection is 0693-0097. Without this approval, we could not conduct this information collection. Public reporting for this information collection is estimated to be approximately 42 hours per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing the information collection. All responses to this information collection are required to obtain benefits. Send comments regarding this burden estimate or any other aspect of this information collection, including suggestions for reducing this burden to the National Institute of Standards and Technology at: askchips@chips.gov.

ACKNOWELDGEMENT [WEB FORM]



COVER PAGE AND APPLICANT PROFILE [WEB FORM]



Cover Page and Applicant Profile (Part 1)

View Confidentiality Statement

Consistent with the Notice of Funding Opportunity (NOFO) for the CHIPS Incentives Program – Facilities for Semiconductor Materials and Manufacturing Equipment, NIST will treat the submitted information as confidential business information (CBI). As a result, NIST will strive to protect the submitted information by applying controls commensurate with the FIPS-199 high for confidentiality level. Information that is populated in structured questions will automatically be labeled as Controlled Unclassified Information – confidential business information (CUI//PROPIN). When uploading free form documents, you are responsible for marking those documents for CBI. Please see the instructions and legend language set forth in the NOFO at section IV.C.2. Proper markings on all submitted information will assist the Department in ensuring protection from disclosure as provided by 15 U.S.C. 4652 (with certain exceptions) and Exemptions 3 and/or 4 of the Freedom of Information Act, 5 U.S.C. 552, as applicable. Please see section IV.C.1 of the NOFO for further information regarding confidentiality.

Complete the cover page and applicant profile questions with the following information regarding the proposed application.

Be sure to include any statements regarding the confidentiality of information contained within the concept plan, in accordance with section IV.C. of the NOFO.

Please provide a short name for your project.

* Name of Application: Company ABC Semi

Applicant Organization Information

Provide the legal name of the entity applying for CHIPS Incentives. Note, this is not the name of the individual submitting the concept plan.

* Potential Applicant Name (i.e., applying entity): MOL1 TESTING 1

Corporate Parent Name:

* Street1: 123 TEST Street

Street2:

* Country/Area: United States | * City: Washington | * State: District of Columbia

* Postal Code: 20010 | * Organization Website: https://chips--uat.sandbox.my.site.com/

Have you registered for a SAM.gov account?

* Response | UEI # : 989898999912

-- No Value --
Yes
No

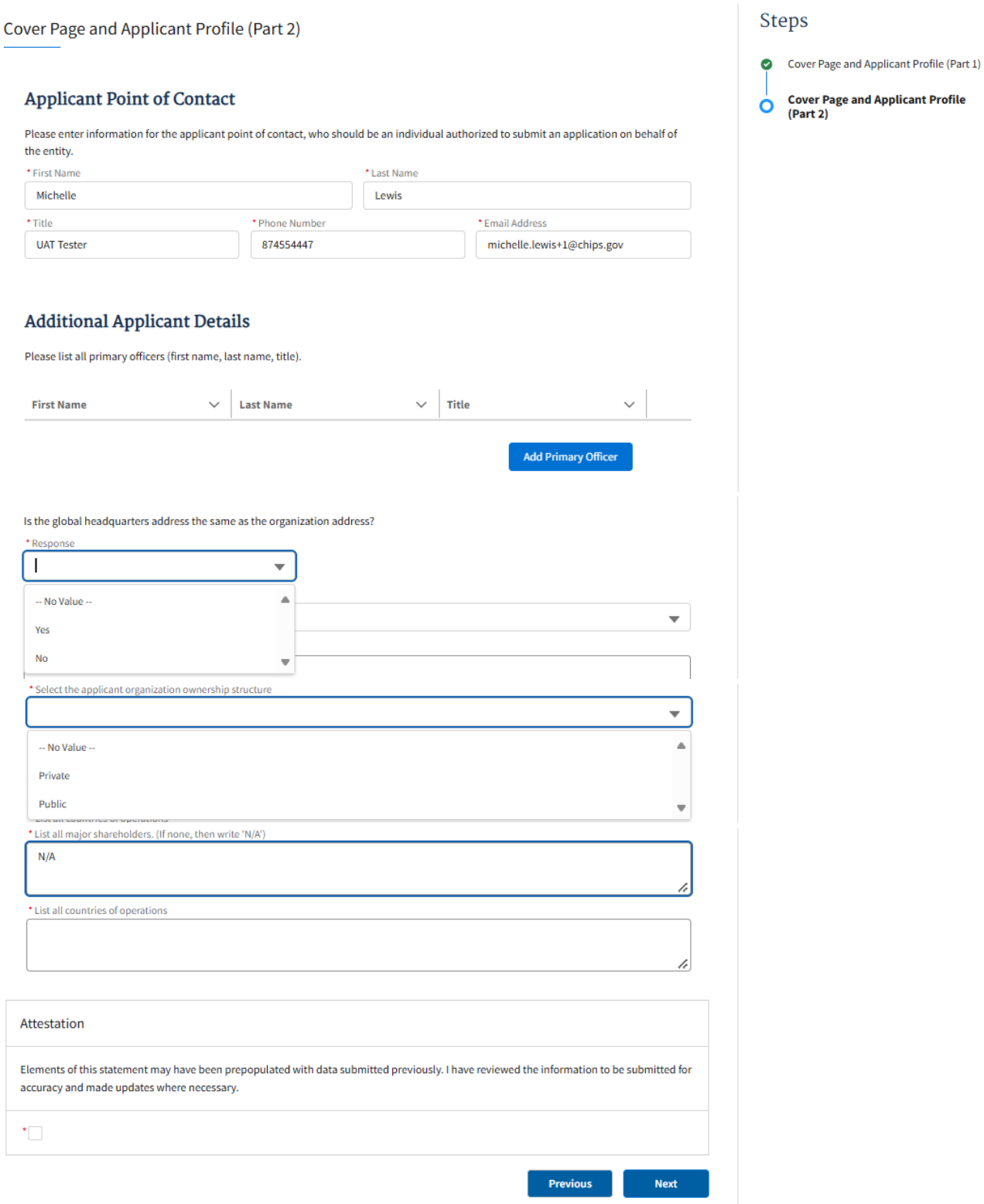
Next

Steps

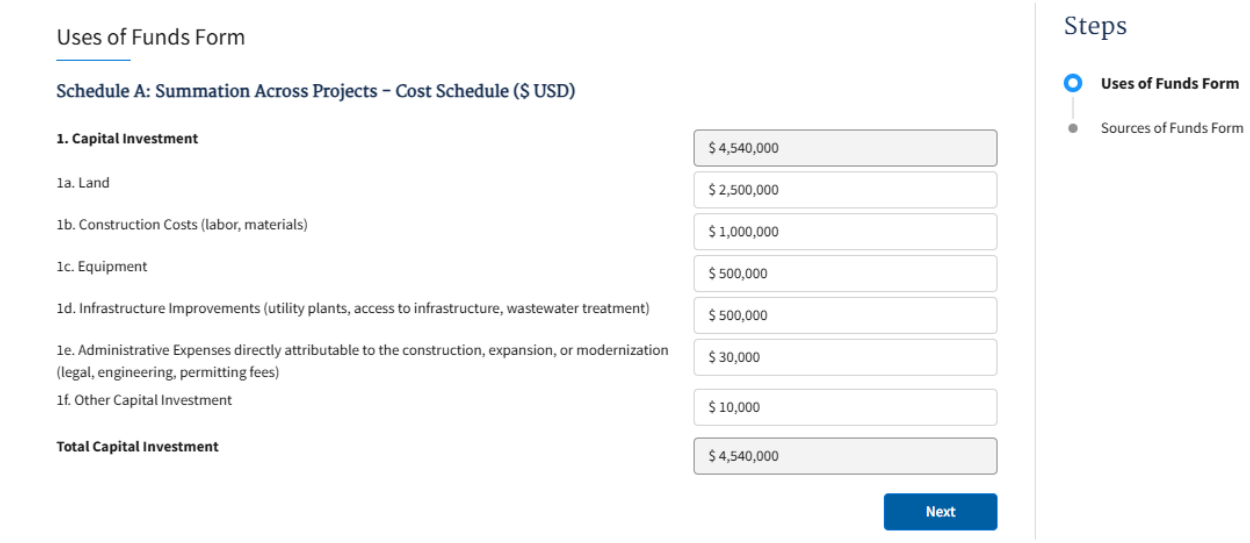
Cover Page and Applicant Profile (Part 1)

Cover Page and Applicant Profile (Part 2)

COVER PAGE AND APPLICANT PROFILE [WEB FORM]



SOURCES AND USES OF FUNDS [WEB FORM]



Uses of Funds Form

Schedule A: Summation Across Projects – Cost Schedule ($ USD)

1. Capital Investment	$ 4,540,000
1a. Land	$ 2,500,000
1b. Construction Costs (labor, materials)	$ 1,000,000
1c. Equipment	$ 500,000
1d. Infrastructure Improvements (utility plants, access to infrastructure, wastewater treatment)	$ 500,000
1e. Administrative Expenses directly attributable to the construction, expansion, or modernization (legal, engineering, permitting fees)	$ 30,000
1f. Other Capital Investment	$ 10,000
Total Capital Investment	$ 4,540,000

Next

Steps

- **Uses of Funds Form**
- Sources of Funds Form



Uses of Funds Form

Schedule A: Summation Across Projects – Cost Schedule ($ USD)

1. Capital Investment	$ 5,800
1a. Land	$ 250
1b. Construction Costs (labor, materials)	$ 100
1c. Equipment	$ 50
1d. Infrastructure Improvements (utility plants, access to infrastructure, wastewater treatment)	$ 5,000
1e. Administrative Expenses directly attributable to the construction, expansion, or modernization (legal, engineering, permitting fees)	$ 300
1f. Other Capital Investment	$ 100
Total Capital Investment	$ 5,800

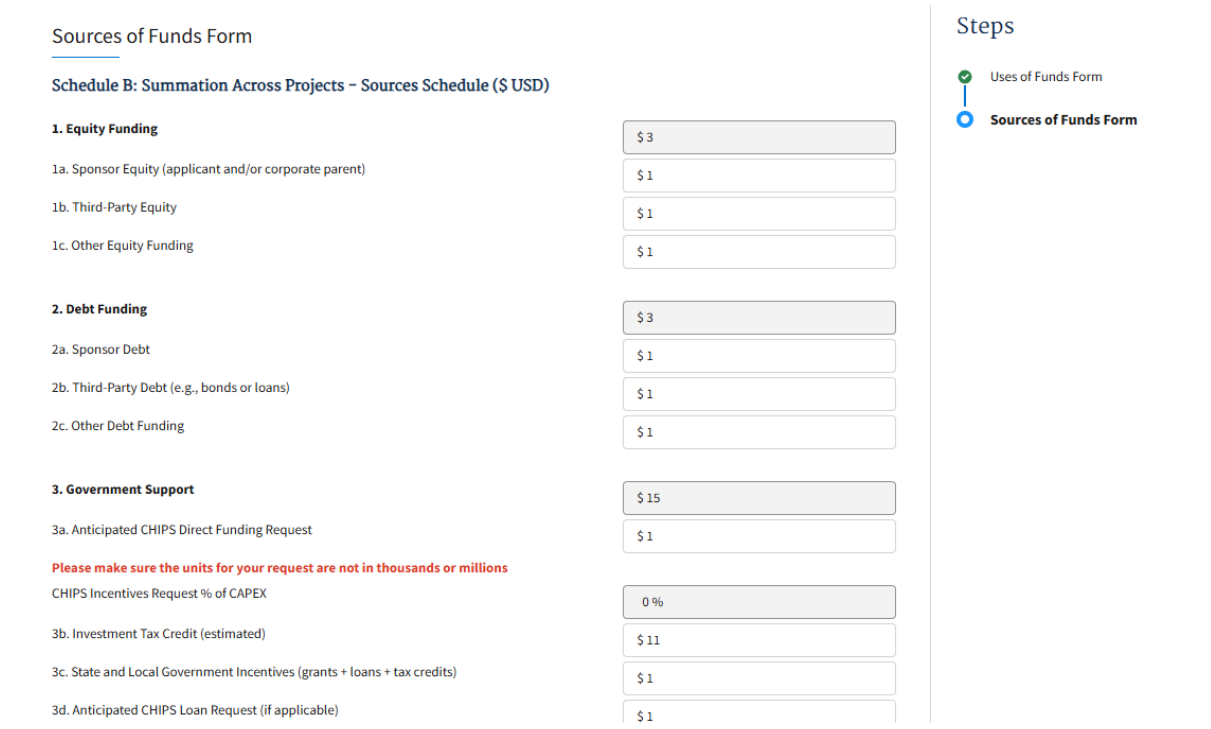
Please make sure the units for your request are not in thousands or millions

Next

Steps

- **Uses of Funds Form**
- Sources of Funds Form

SOURCES AND USES OF FUNDS [WEB FORM]



Sources of Funds Form

Schedule B: Summation Across Projects – Sources Schedule ($ USD)

1. Equity Funding	$ 3
1a. Sponsor Equity (applicant and/or corporate parent)	$ 1
1b. Third-Party Equity	$ 1
1c. Other Equity Funding	$ 1
2. Debt Funding	$ 3
2a. Sponsor Debt	$ 1
2b. Third-Party Debt (e.g., bonds or loans)	$ 1
2c. Other Debt Funding	$ 1
3. Government Support	$ 15
3a. Anticipated CHIPS Direct Funding Request	$ 1

Please make sure the units for your request are not in thousands or millions

CHIPS Incentives Request % of CAPEX	0 %
3b. Investment Tax Credit (estimated)	$ 11
3c. State and Local Government Incentives (grants + loans + tax credits)	$ 1
3d. Anticipated CHIPS Loan Request (if applicable)	$ 1

Steps

- Uses of Funds Form
- **Sources of Funds Form**

SOURCES AND USES OF FUNDS [WEB FORM]

Sources of Funds Form

Schedule B: Summation Across Projects – Sources Schedule ($ USD)

1. Equity Funding	$ 50,000
1a. Sponsor Equity (applicant and/or corporate parent)	$ 50,000
1b. Third-Party Equity	$ 0
1c. Other Equity Funding	$ 0
2. Debt Funding	$ 1,000,000
2a. Sponsor Debt	$ 1,000,000
2b. Third-Party Debt (e.g., bonds or loans)	$ 0
2c. Other Debt Funding	$ 0
3. Government Support	$ 7,120,000
3a. Anticipated CHIPS Direct Funding Request	$ 5,000,000
CHIPS Incentives Request % of CAPEX	110.13 %
3b. Investment Tax Credit (estimated)	$ 120,000
3c. State and Local Government Incentives (grants + loans + tax credits)	$ 0
3d. Anticipated CHIPS Loan Request (if applicable)	$ 1,000,000
3e. Guaranteed portion of Third-Party Loans Expected to be Guaranteed by CHIPS Program (if applicable)	$ 1,000,000
4. Other Sources of Funds	$ 0
Total Project Funding	$ 8,170,000

Provide a CHIPS Incentives Justification (max. 1500 characters)

Write justification here

Previous Next

Steps

- Uses of Funds Form
- **Sources of Funds Form**

CONCEPT PLAN PROJECT INFORMATION [WEB FORM]



Consortium and Partner Information

Consortium

Is the applicant part of a consortium?

* Response

-- No Value --
Yes
No

Are there other entities (e.g. customers, suppliers, investors, advisor(s)) you anticipate partnering with in a meaningful way?

* Response

Next



Consortium and Partner Information

Consortium

Is the applicant part of a consortium?

* Response

No

Partnering Entities, if applicable

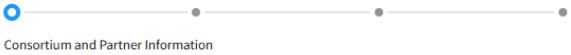
Are there other entities (e.g. customers, suppliers, investors, advisor(s)) you anticipate partnering with in a meaningful way?

* Response

-- No Value --
Yes
No
Not determined at this time

Next

CONCEPT PLAN PROJECT INFORMATION [WEB FORM]



Consortium and Partner Information

Consortium

Is the applicant part of a consortium?

* Response

Yes

Please note: if you change your consortium status selections before submitting your application, it is possible that a new consortium key will be generated. Please take note of any updated keys for your consortium partners.

Has anyone from the consortium already applied?

* Response

No

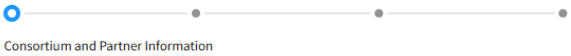
You will be given your consortium key on the following screen. Please share this key with your consortium partners to use in their application.

* Consortium Title

Title

* Consortium Description

Description



Consortium and Partner Information

Consortium

Is the applicant part of a consortium?

* Response

Yes

Please note: if you change your consortium status selections before submitting your application, it is possible that a new consortium key will be generated. Please take note of any updated keys for your consortium partners.

Has anyone from the consortium already applied?

* Response

No

You will be given your consortium key on the following screen. Please share this key with your consortium partners to use in their application.

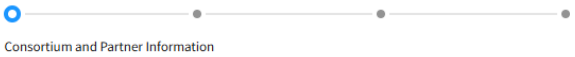
* Consortium Title

Title

* Consortium Description

Description

CONCEPT PLAN PROJECT INFORMATION [WEB FORM]



Consortium and Partner Information

Consortium

Is the applicant part of a consortium?

* Response

Yes

Please note: if you change your consortium status selections before submitting your application, it is possible that a new consortium key will be generated. Please take note of any updated keys for your consortium partners.

Has anyone from the consortium already applied?

* Response

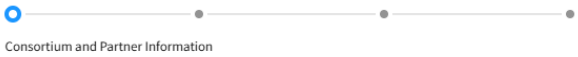
Yes

Please provide the consortium key. This was generated when another member of the consortium applied.

* Consortium Key

4422-ptptptp

CONCEPT PLAN PROJECT INFORMATION [WEB FORM]



Consortium and Partner Information

Consortium

Is the applicant part of a consortium?

* Response

No

Partnering Entities, if applicable

Are there other entities (e.g. customers, suppliers, investors, advisor(s)) you anticipate partnering with in a meaningful way?

* Response

Not determined at this time

Next

Consortium and Partner Information

Consortium

Is the applicant part of a consortium?

* Response

No

Partnering Entities, if applicable

Are there other entities (e.g. customers, suppliers, investors, advisor(s)) you anticipate partnering with in a meaningful way?

* Response

Yes

Please list each partner and describe their role in the project. (max. 1500 characters)

* Response

Partner list here

Next

CONCEPT PLAN PROJECT INFORMATION [WEB FORM]



Project Information

Organizations proposing multiple projects or facilities that are not co-located with one another should submit separate concept plans and applications per project location for consideration.

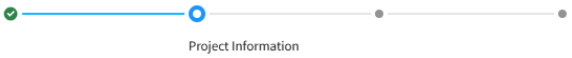
Site Location

City | State | ZIP Code

-- No Value --

Site location not yet known

Previous | Next



Project Information

Organizations proposing multiple projects or facilities that are not co-located with one another should submit separate concept plans and applications per project location for consideration.

Site Location

* City: Washington

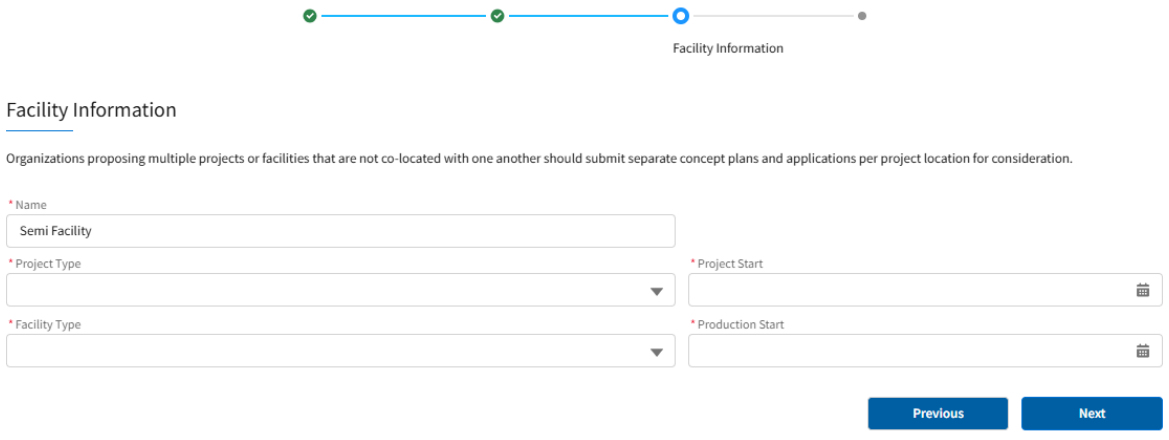
* State: District of Columbia

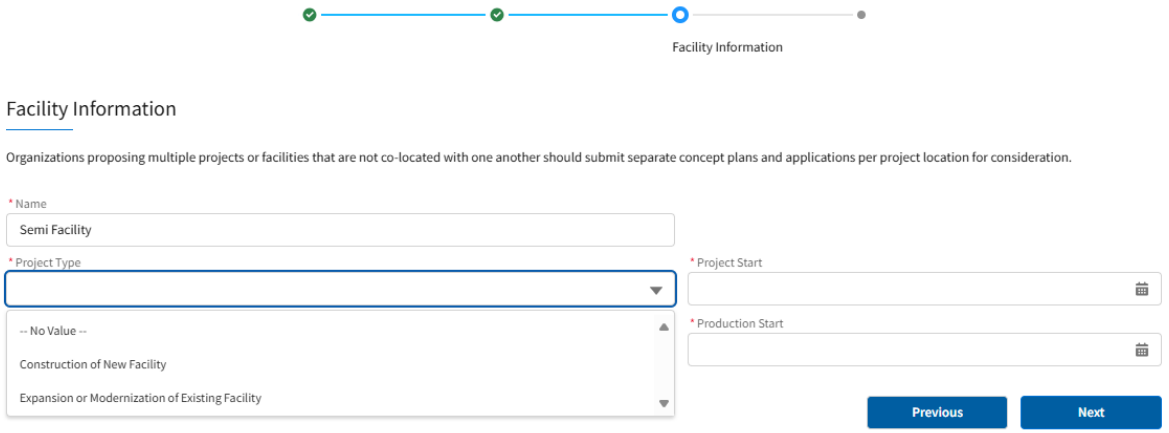
* ZIP Code: 20010-0000

Site location not yet known

Previous | Next

CONCEPT PLAN PROJECT INFORMATION [WEB FORM]





CONCEPT PLAN PROJECT INFORMATION [WEB FORM]



Facility

A "facility" used in the context of this application refers to a semiconductor materials facility or semiconductor manufacturing equipment facility that will be constructed, expanded, or modernized as a result of this project. Please refer to the NOFO section I.B.1 for additional description of semiconductor materials or manufacturing equipment facilities covered by this NOFO.

Total Number of Facilities: 1

Name	Project Type	Facility Type	Number of Materials / Equipment Produced
Semi Facility	Construction of New Facility	Semiconductor Materials Facilities	0

EQUIPMENT 1 New

Equipment Type	Peak Monthly Capacity	Unit of Production	Cost Per Unit Of Production ($ U...	Projected Price per Unit ($ USD)	

MATERIALS 2 New

Material Type	Peak Monthly Capacity	Unit of Production	Cost Per Unit Of Production ($ U...	Projected Price per Unit ($ USD)	

Previous Next



Facility

A "facility" used in the context of this application refers to a semiconductor materials facility or semiconductor manufacturing equipment facility that will be constructed, expanded, or modernized as a result of this project. Please refer to the NOFO section I.B.1 for additional description of semiconductor materials or manufacturing equipment facilities covered by this NOFO.

Total Number of Facilities: 1

Name	Project Type	Facility Type	Number of Materials / Equipment Produced
Semi Facility	Construction of New Facility	Semiconductor Materials Facilities	0

EQUIPMENT 1 New

Equipment Type	Peak Monthly Capacity	Unit of Production	Cost Per Unit Of Production ($ U...	Projected Price per Unit ($ USD)	

* Equipment Type
--Select--

* Peak Monthly Capacity
12345

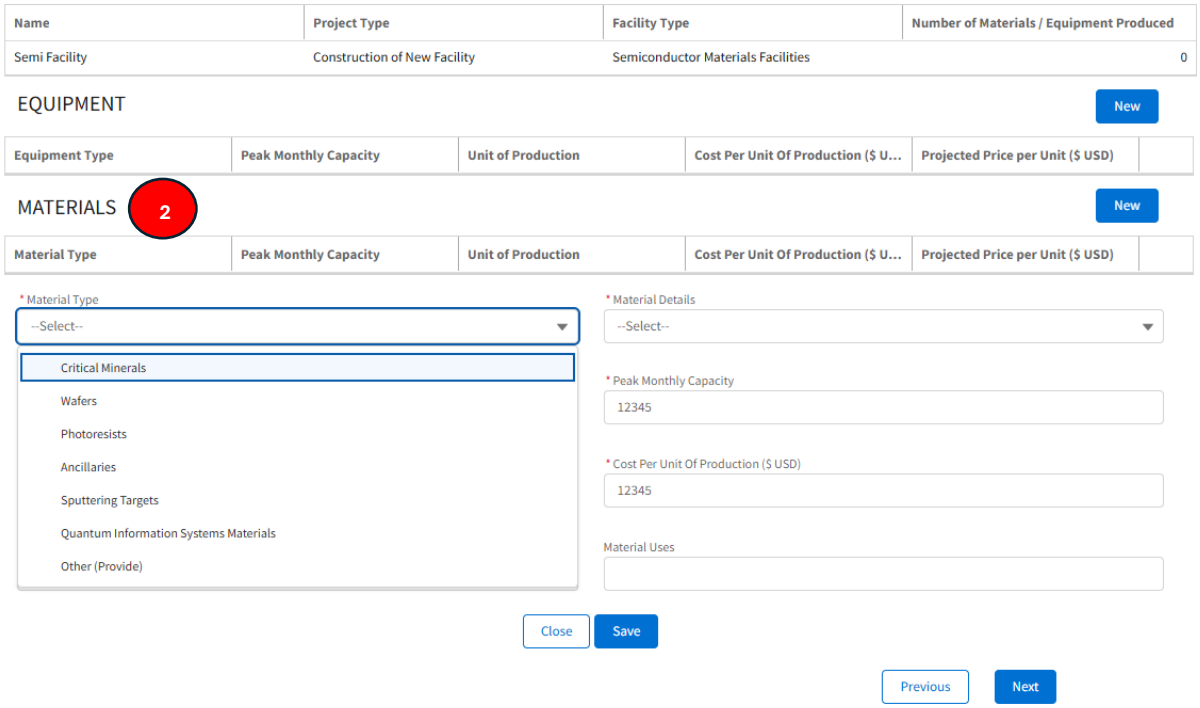
* Unit of Production

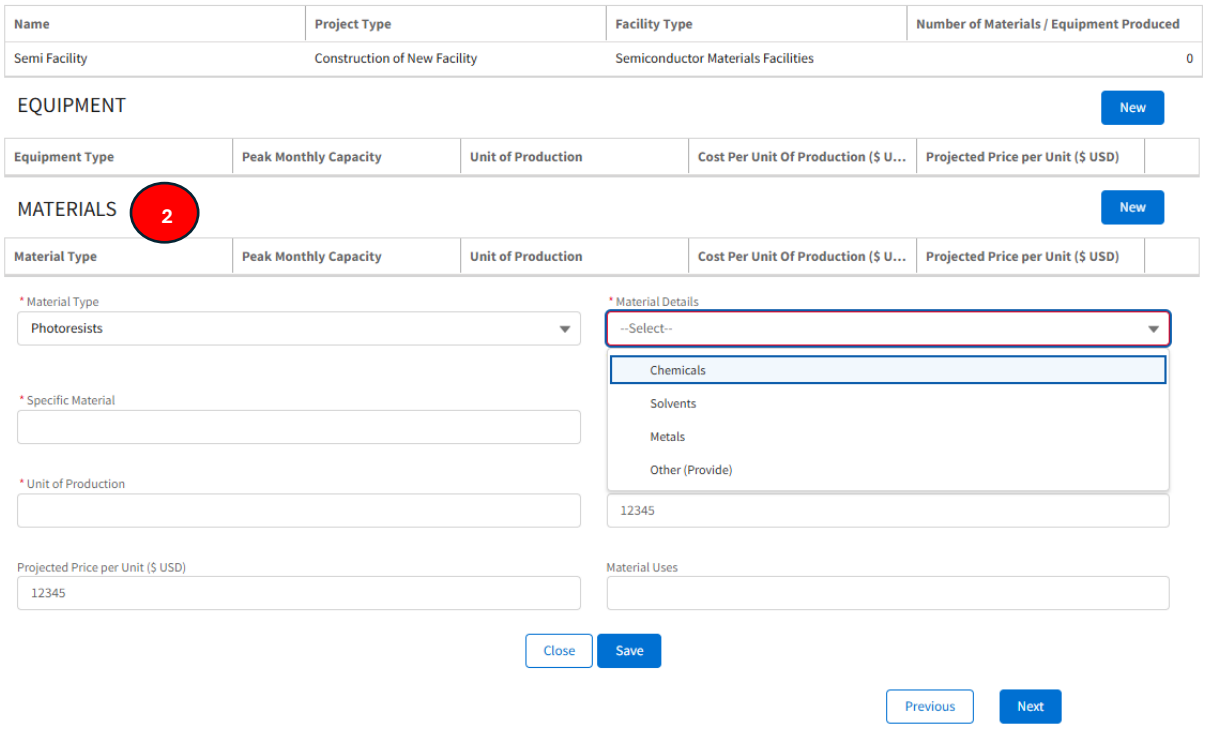
* Cost Per Unit Of Production ($ USD)
12345

Projected Price per Unit ($ USD)
12345

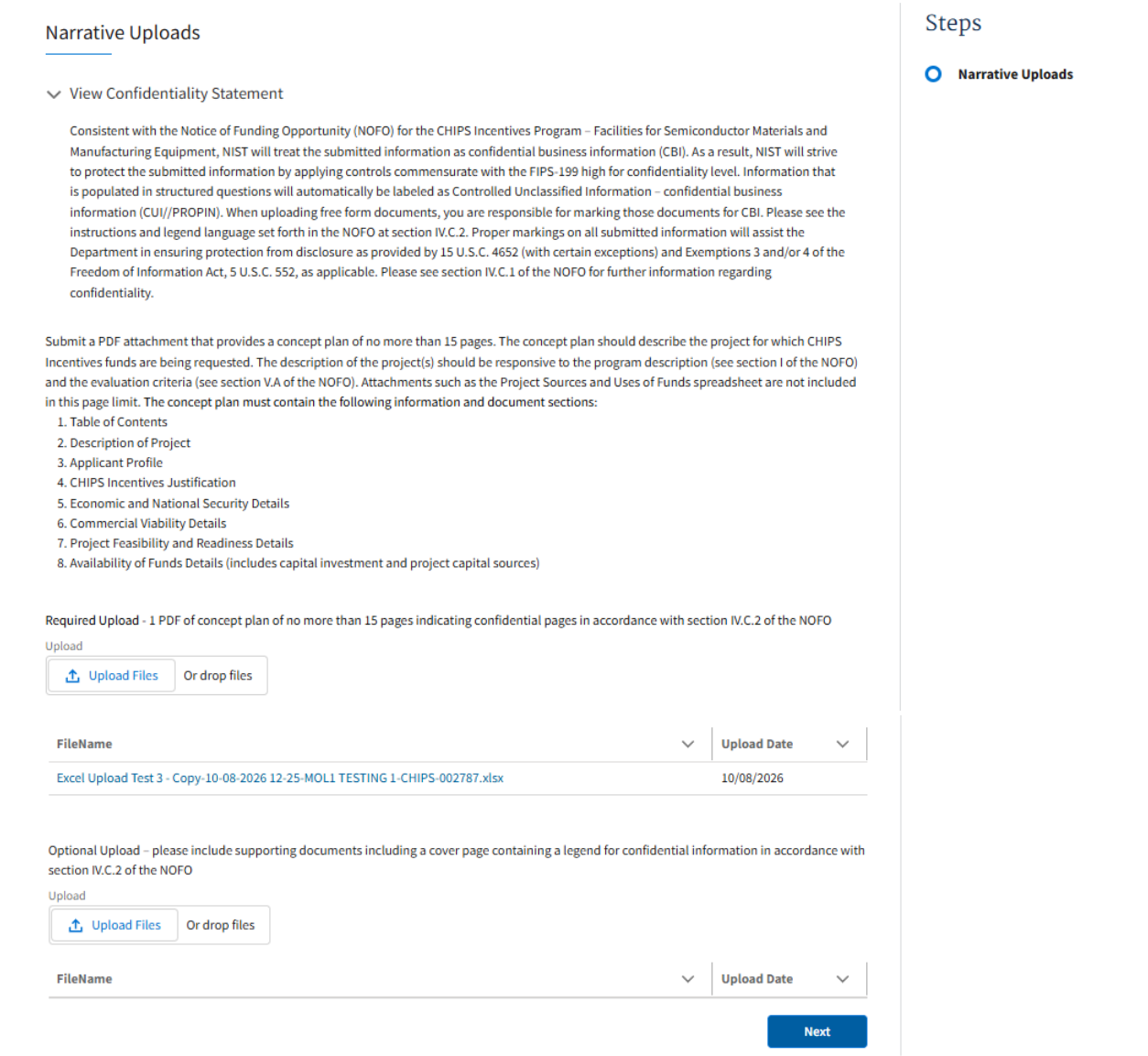
Close Save

CONCEPT PLAN PROJECT INFORMATION [WEB FORM]

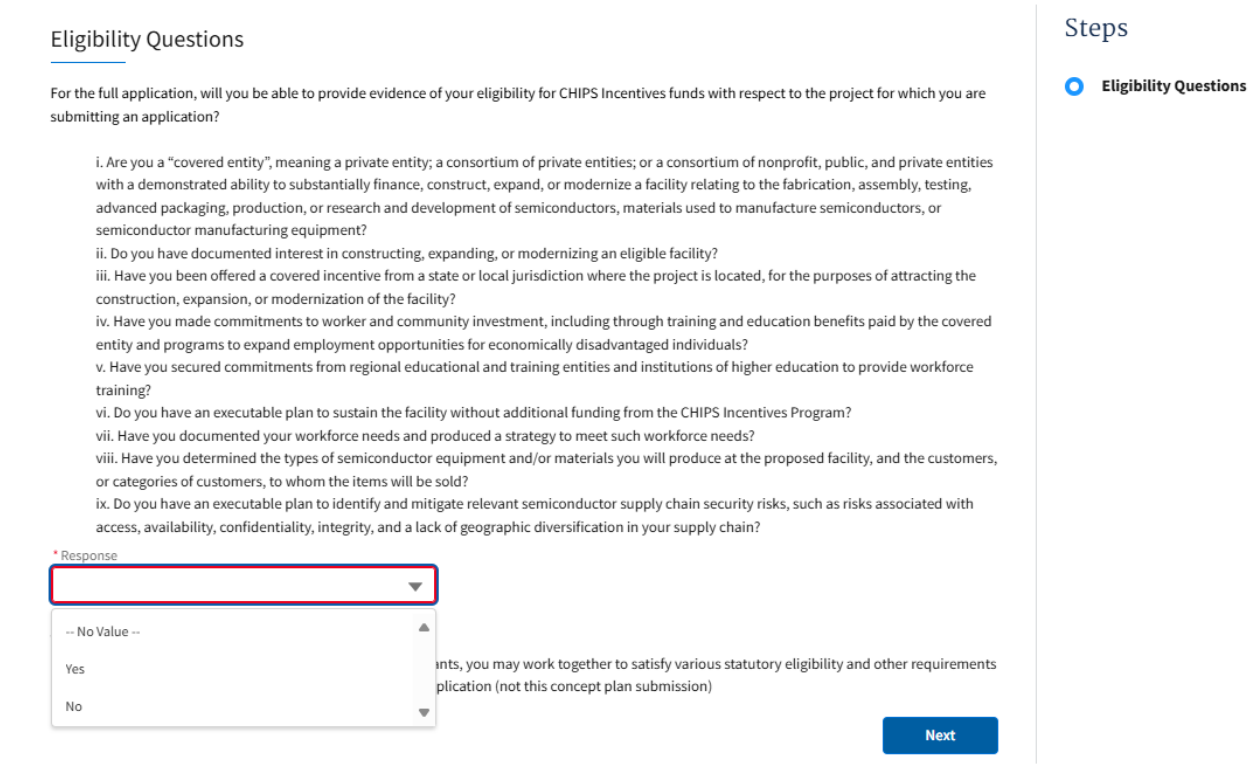




NARRATIVE UPLOADS



CONFIRM ABILITY TO SUBMIT A FULL APPLICATION [WEB FORM]



ATTESTATION AND SUBMISSION [WEB FORM]

Attest and Submit

The CHIPS Program Office (CPO) recognizes the importance of protecting confidential business information and will follow all applicable laws to protect such information, including, for example, the CHIPS Act, the Trade Secrets Act, and the Freedom of Information Act. Please refer to section IV.C. of the CHIPS Incentives Program – Facilities for Semiconductor Materials and Manufacturing Equipment (CHIPS-SMME) for a further discussion of these laws.

Submission Certifications

Attestation

The individual submitting the concept plan certifies on behalf of the applicant entity that the applicant information and data submitted and the representations made in the concept plan are true, complete and accurate, to the best of the applicant's knowledge and belief after due inquiry.

* ☑

Attestation

The individual submitting the concept plan certifies on behalf of the applicant that the applicant understands that CPO and the Department of Commerce will rely on the accuracy and completeness of the applicant information and data submitted and the representations made in the concept plan and that any false, fictitious, or fraudulent statement or representation made in the concept plan may be the basis for rejection of the concept plan or subject the applicant to criminal, civil, or administrative penalties. (18 U.S. Code, section 1001.)

* ☑

Attestation

The individual submitting the concept plan certifies on behalf of the applicant that the applicant understands that any applicant information and data contained in the concept plan may be accessed and used by federal employees, consultants and contractors in accordance with CHIPS-SMME, section IV.C. (Confidential Information)

* ☑

Attestation

The individual submitting the concept plan certifies that they possess the full legal power and authority to submit the concept plan and make the preceding certifications on behalf of this applicant.

* ☑

Public Communications

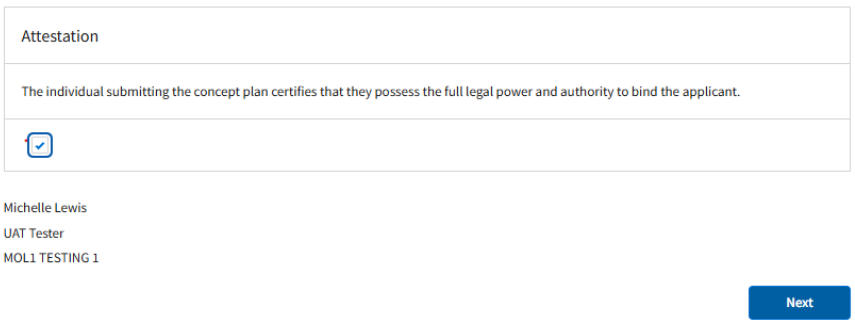
Attestation

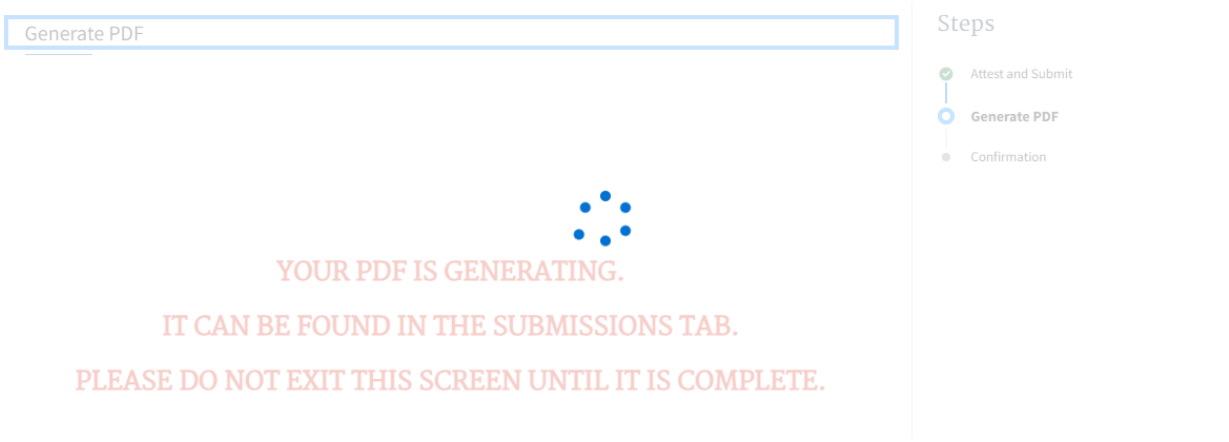
The individual submitting the concept plan agrees that neither the applicant entity nor any of its affiliates may issue any press release or otherwise publicly disclose the status of the concept plan or the contents of any communications with CPO or the Department of Commerce without CPO's prior written consent.

* ☑

Steps

- **Attest and Submit**
- Generate PDF
- Confirmation


Attestation
The individual submitting the concept plan certifies that they possess the full legal power and authority to bind the applicant.
Michelle Lewis
UAT Tester
MOL1 TESTING 1
Next


Generate PDF
Steps
Attest and Submit
Generate PDF
Confirmation
YOUR PDF IS GENERATING.
IT CAN BE FOUND IN THE SUBMISSIONS TAB.
PLEASE DO NOT EXIT THIS SCREEN UNTIL IT IS COMPLETE.


Confirmation
Your document has been generated and can be found in the Submissions tab.
Finish
Steps
Attest and Submit
Generate PDF
Confirmation


Concept Plan
OMB Control Number: 0693-0097
Expiration Date: 11/30/2026
(The above date is not the submission deadline.)
View Burden Statement
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SECTION STATUS
Submitted
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SECTION STATUS
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SECTION STATUS
Submitted
Submitted
Narrative Uploads
SECTION STATUS
Submitted
Submitted
Confirm Ability to Submit a Full Application [Web Form]
SECTION STATUS
Submitted
Submitted
Attestation and Submission [Web Form]
SECTION STATUS
Submitted
Submitted